

## **ABSTRACT**

A heat dissipating device with heat conductive posts comprises a substrate made of aluminum; a lower portion of the substrate being formed with a plurality of via holes; a plurality of heat conductive posts made of copper. The heat conductive posts being embedded into the via holes of the substrate. A plurality of heat dissipating fins on one surface of the base. In manufacturing process, the substrate enters into a through hole of a shaping mold and then enters into a clip to be clamped by the clip so that the ribs on the surface of the heat conductive posts are embedded into inner walls of the via holes. Then, the whole substrate passes through the clip so be compressed by the clip. Thereby, the heat conductivity of the substrate is changed by embedding with the heat conductive posts.